Congratulations to the 26 Newly Elected
IEEE Electron Devices Society Fellows
Effective January 1, 2017

Hugh Barnaby, Arizona State University, Tempe, Arizona, USA
for research of radiation effects in bipolar junction transistors

Yu Cao, Arizona State University, Tempe, Arizona, USA
for development of predictive technology models for reliable circuit and system integration

Edoardo Charbon, Delft University of Technology, Delft, Netherlands
for contributions to solid-state single photon avalanche detectors and their applications in imaging

Wei-ting Chien, SMIC-Semiconductor Mfg. Int'l Corp., Shanghai, China
for leadership in reliability management

Terry Ericsen, Ericsen Innovations LLC, Annapolis, Maryland, USA
for leadership in power electronics

Christopher Hierold, Swiss Federal Institute of Technology, Zurich, Switzerland
for contributions to microelectromechanical sensors and microthermoelectric energy harvesting

Ru Huang, Peking University, Beijing, China
for contributions to multi-gate silicon nanowire transistor technology

Tian-wei Huang, National Taiwan University, Taipei, Taiwan
for contributions to design and development of millimeter-wave CMOS RFICs

Chia-hong Jan, Intel Corporation, Portland, Oregon, USA
for leadership in developing low power logic technologies for System-on-Chip

Quanxi Jia, University of Buffalo, Buffalo, New York, USA
for contributions to coated superconductors and metal-oxide thin films for electronic applications

Hongrui Jiang, University of Wisconsin, Madison, Wisconsin, USA
for contributions to materials and micro-scale optical tools for medical imaging

Richard King, Arizona State University, Tempe, Arizona, USA
for contributions to high-performance space and terrestrial photovoltaics technology

Hulya Kirkici, Auburn University, Auburn, Alabama, USA
for contributions to high frequency, high field dielectric breakdown and electrical insulation for space and aerospace power systems

Steven Koester, University of Minnesota, Minneapolis, Minnesota, USA
for contributions to group-IV electronic and photonic devices

Xiuling Li, University of Illinois, Champaign, Illinois, USA
for contributions to semiconductor nanomaterials for electronic and photonic applications

**Donald Y. Lie**, Texas Tech University, Lubbock, Texas, USA
for contributions to high linearity and high efficiency silicon RF power amplifiers for broadband wireless applications

**Theresa Mayer**, Virginia Tech, Blacksburg, Virginia, USA
for contributions to nanomaterials integration and directed assembly

**Junichi Nakamura**, Brillnics Japan Inc., Tokyo, Japan
for leadership in CMOS image sensors

**Borivoje Nikolic**, University of California, Berkeley, California, USA
for contributions to energy-efficient design of digital and mixed-signal circuits

**Akihiro Nitayama**, Tohoku University, Sendai, Japan
for leadership in 3-dimensional NAND Flash memory technology development

**Tomas Palacios**, Massachusetts Institute of Technology, Cambridge, Massachusetts, USA
for contributions to gallium nitride electron devices and two-dimensional materials

**Dimitrios Peroulis**, Purdue University, West Lafayette, Indiana, USA
for contributions to MEMS-based tunable filters

**Ramgopal Raovalipe**, Indian Institute of Technology, Powai, Mumbai, India
for contributions to CMOS System-on-Chip technologies

**Andrei Vladimirescu**, Berkeley Wireless Research Center, Berkeley, California, USA
for contributions to the development and commercial adoption of SPICE circuit simulation

**Sorin Voinigescu**, University of Toronto, Toronto, Ontario, Canada
for contributions to silicon and silicon-germanium microwave and millimeter-wave devices and integrated circuits

**Xin Zhang**, Boston University, Boston, Massachusetts, USA
for contributions to microelectromechanical systems

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**Paul K.L. Yu**
2017 EDS Fellows Chair
University of California at San Diego
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